

Title (en)
Inductor device

Title (de)
Drosselspuleanordnung

Title (fr)
Dispositif d'inductance

Publication
EP 0694932 B1 20030226 (EN)

Application
EP 95304759 A 19950707

Priority
GB 9415316 A 19940729

Abstract (en)
[origin: EP0694932A1] An inductor device for a multichip module, surface-mount or direct-chip attach assembly is formed on a chip or substrate of a dielectric material, high resistivity semiconductor or ferrite as a spiral metallisation, with solder bumps formed on the terminations of the spiral for connection to corresponding conductors on the underlying surface of the assembly. The use of the flip chip solder bonding technique ensures precise lateral alignment and vertical spacing of the chip with respect to the underlying surface. <MATH>

IPC 1-7
H01F 17/00; **H01F 27/29**

IPC 8 full level
H01F 27/06 (2006.01); **H01F 17/00** (2006.01); **H01F 27/29** (2006.01)

CPC (source: EP)
H01F 17/0006 (2013.01); **H01F 27/292** (2013.01)

Cited by
US6933205B2; DE19854234C1; EP1553700A3; US6713375B2; US6310386B1; EP1553700A2; WO0201638A3; WO2013070371A1;
US8539666B2; US9159485B2

Designated contracting state (EPC)
AT DE ES FR IT

DOCDB simple family (publication)
EP 0694932 A1 19960131; **EP 0694932 B1 20030226**; AT E233428 T1 20030315; DE 69529709 D1 20030403; GB 2292016 A 19960207;
GB 2292016 B 19980722; GB 9415316 D0 19940921; JP H0864422 A 19960308

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EP 95304759 A 19950707; AT 95304759 T 19950707; DE 69529709 T 19950707; GB 9415316 A 19940729; JP 20922295 A 19950725